Product Change Notification - JAON-03NWIE880

Date: 16 Mar 2015

Notification subject: CCB 1540.01 Initial Notice: Qualification of 24AA515, 24FC515, and 24LC515 device familie

Notification text:

PCN Status:
Initial notification

Microchip Parts Affected:
See attachments of affected catalog part numbers (CPN) labeled as…
PCN_JAON-03NWIE880_Affected_CPN.xls
PCN_JAON-03NWIE880_Affected_CPN.pdf

Description of Change:
Qualification of 24AA515, 24FC515, and 24LC515 device families in 8L PDIP packa

Pre Change:
MTAI assembly site

Post Change:
MMT assembly site

Impacts to Data Sheet:
None

Reason for Change:
To improve productivity by qualifying MMT assembly site.

Change Implementation Status:
In Progress

Estimated First Ship Date:
May 20, 2015 (date code: 1521)

NOTE: Please be advised that after the estimated first ship date customers may re

Markings to Distinguish Revised from Unrevised Devices:
Traceability code

Revision History:
March 16, 2015: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory com
the applicable products.

Attachment(s):
PCN_JAON-03NWIE880_Qual_Plan.pdf
PCN_JAON-03NWIE880_Affected_CPN.pdf
PCN_JAON-03NWIE880_Affected_CPN.xls

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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MICROCHIP

QUALIFICATION PLAN

PCN #: JAON-03NWIE880

Date:
Feb. 26, 2015

Qualification of 24AA515, 24FC515, and 24LC515 device families in 8L PDIP package at MMT assembly site.

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Purpose: Qualification of 24AA515, 24FC515, and 24LC515 device families in 8L PDIP package at MMT assembly site.

MP code: 360017C4XA00

Part No.: 24LC515-I/P

BD No: BDM-000722 rev. A (Engineering BD)

CCB No.: 1540.01

Package:

Type 8L PDIP

Width or Size 150 mils

Die thickness: Bottom Die: 11 mils
Top Die: 8 mils

Die size: Bottom Die: 119.20 x 143.10 mils
Top Die: 78.30 x 105.60 mils

Lead frame:

Paddle size: 140 x 180 mils

Material CD194

Surface Ag Spot Plated

Process Stamped

Lead Lock Yes

Part Number 10100833

Treatment None

Wire:

Material Au

Die Attach Epoxy:

Part Number CRM-1064L

Conductive Yes

Mold Compound: GE800

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	Special Instructions
Wire Bond Pull - WBP	Mil. Std. 883-2011	5	0	1	5	0 fails after TC	5	30 bonds from a minimum of 5 devices.
Wire Bond Shear - WBS	CDF-AEC-Q100-001	5	0	1	5	0	5	30 bonds from a minimum of 5 devices.
Bond Line Thickness (BLT) robustness assessment		5	1	3	15	>0.5 mils		For Engineering Info only. Recommended for packages where the die is susceptible to cracking and for packages where a non-conductive die attach is used when the substrate is referenced to V_{DD} vs. ground. but should be tested during Package Qualification
External Visual	Mil. Std. 883-2009/2010	All devices prior to submission for qualification testing	0	3	ALL	0	5	
HTSL (High Temp Storage Life)	+175 C for 504 hours or 150°C for 1008 hrs. Electrical test pre and post stress at +25C and hot temp. (1 lot to be tested 85C)	45	5	1	50	0	10	Must be in progress at time of package release to production, but completion is not required for release to production.
HAST	+130°C/85% RH for 96 hours. Electrical test pre and post stress at +25°C and hot temp. (1 lot to be tested 85C)	77	5	3	246	0	10	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
Unbiased HAST	+130°C/85% RH for 96 hrs. Electrical test pre and post stress at +25°C.	77	5	3	246	0	10	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
Temp Cycle	-65°C to +150°C for 500 cycles. Electrical test pre and post stress at hot temp; 3 gram force WBP, on 5 devices from 1 lot, Test by following readpoint TC 500. (1 lot to be tested 85C)	77	5	3	246	0	15	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.

PCN_JAON-03NWIE880
CATALOG_PART_NBR
24AA515-I/P
24FC515-I/P
24LC515-I/P